TECHNICAL SPEC FOR Spin etcher

System Model:
SEZ RST200

Wafer size: 6 inch

Chamber count: 1

Chamber type: single (multi) chamber

CDS: RST100

DIW Arm: medium dispenser for 3 medium & DIW

N2 Arm:

Load system: ECO handling system

Swivel levers: installed

Chuck: pins

Heater exchanger: remote temperature control units, filled with water

Temperature: indirect temp control ranges +10degC to +50degC

Dry N2 Monitor:

Suck back system: installed

Pumps: buffer, drain, process

Suck back valve: suck back unit with 4 valves (medium1,2,3 & DIW)

Wafer defect system:

Endpoint Detection System: NA

Ozone processing: NA

Robot:

Thin-wafer handling:

Chemicals used: HF, HNO3, DIW

SECS:

Vintage:

Missing parts:

Defected parts:

Software: DOS

Operating system: 486 system?

Photos to Collect

- All 4 sides
    - Process console
    - Electronic console
    - Canister console
- Control panel
- Turntable
- Inside all cabinets (boards, electronics and chemicals)
- Serial plate
- Spare parts, manuals (if any)